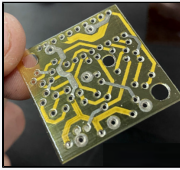
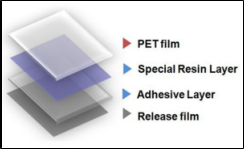


# Multi-layer film forming

## APPLICATIONS

<p><b>Electronics</b></p> 	<p><b>IC substrate manufacturing</b></p>
<p><b>Film formation</b></p> 	<p><b>Multi-layer film manufacturing</b></p>

## KNOWLEDGE & MODELS

Process	Vacuum Hot Press
Material	Polyimide Film
	Cu Foil
	Prepreg
Simulation (VE)	bending of FCCL

## CAPABILITIES

<p><b>Core Equipments at ADL Ewha Site</b></p>
<p>Hot Press Machine</p>

Ewha	<p><b>Core Competitiveness at ADL</b></p>
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## Evaluation Data Library

Customized Products	Liquid Crystal Polymer Products
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## Project History

No	Project Title
1	Flexible Copper Clad Laminate development
2	
3	

<p>Film Lamination Processing of Microelectronics</p>
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